L Number	Hits	Search Text	DB	Time stamp
-	114427	electroplat\$4 or electro adj2 plat\$4 or	USPAT;	2004/09/01 13:03
		electrodeposit\$4 or electrol\$8 near3	US-PGPUB;	
		deposit\$4 or electrochemical\$2 near3	EPO; JPO;	
		deposit\$ or (electro adj1 chemical\$2)	DERWENT;	
	051600	near3 deposit\$4	IBM TDB	2004/00/01 12:05
_	251638	seed\$4	USPAT; US-PGPUB;	2004/09/01 13:05
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	1837550	fill\$4 or refill\$4	USPAT;	2004/09/01 10:12
			US-PGPUB;	·
			EPO; JPO;	
1			DERWENT;	
	1150000		IBM_TDB	0004/00/01 00:00
-	1159899	copper or cu	USPAT;	2004/09/01 09:02
			US-PGPUB; EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	697397	photoresist or resist or photosensitive or	USPAT;	2004/09/01 12:58
1		photo adj2 sensitive	US-PGPUB;	
1	!		EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	1173993	wiring or interconnect\$4 or inter adj2	USPAT;	2004/09/01 09:04
	·	connect\$4	US-PGPUB;	
			EPO; JPO; DERWENT;	
			IBM TDB	
-	392748	harden\$4	USPAT;	2004/09/01 09:42
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
	5050000		IBM_TDB	2004/00/01 12:04
_	5058080	groove or trench or hole or aperture or	USPAT; US-PGPUB;	2004/09/01 13:04
		opening	EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	7713	(copper or cu) with (fill\$4 or refill\$4)	USPĀT;	2004/09/01 10:14
		with (groove or trench or hole or aperture	US-PGPUB;	
		or opening)	EPO; JPO;	
			DERWENT;	
_	13795	 seed\$4 with (groove or trench or hole or	IBM_TDB USPAT;	2004/09/01 10:14
	13793	aperture or opening)	US-PGPUB;	2004/05/01 10:14
		aporture or opening,	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	597	(electroplat\$4 or electro adj2 plat\$4 or	USPAT;	2004/09/01 10:17
		electrodeposit\$4 or electrol\$8 near3	US-PGPUB;	
		deposit\$4 or electrochemical\$2 near3	EPO; JPO;	
		deposit\$ or (electro adj1 chemical\$2) near3 deposit\$4) same ((copper or cu) with	DERWENT; IBM TDB	
		(fill\$4 or refill\$4) with (groove or	15.1_100	
		trench or hole or aperture or opening))		
		same (seed\$4 with (groove or trench or		
		hole or aperture or opening))		
-	276	((electroplat\$4 or electro adj2 plat\$4 or	USPAT;	2004/09/01 14:28
		electrodeposit\$4 or electrol\$8 near3	US-PGPUB;	
		deposit\$4 or electrochemical\$2 near3	EPO; JPO; DERWENT;	
		deposit\$ or (electro adj1 chemical\$2) near3 deposit\$4) same ((copper or cu) with	IBM TDB	
		(fill\$4 or refill\$4) with (groove or		
		trench or hole or aperture or opening))		
		same (seed\$4 with (groove or trench or		
		hole or aperture or opening))) and		
		(photoresist or resist or photosensitive		
		or photo adj2 sensitive)		

-	114427		USPAT;	2004/09/01 12:58
		electrodeposit\$4 or electrol\$8 near3	US-PGPUB;	
ì		deposit\$4 or electrochemical\$2 near3	EPO; JPO;	
		deposit\$ or (electro adj1 chemical\$2)	DERWENT;	,
		near3 deposit\$4	IBM_TDB	
-	995720	photoresist or resist or photosensitive or	USPAT;	2004/09/01 12:59
Į		photo adj2 sensitive or polymeric	US-PGPUB;	
]			EPO; JPO;	
			DERWENT;	
ļ			IBM_TDB	
-	2422381	(photoresist or resist or photosensitive	USPAT;	2004/09/01 13:00
		or photo adj2 sensitive or polymeric) or	US-PGPUB;	
		polymer or polyimide	EPO; JPO;	
			DERWENT;	
			IBM TDB	
-	1175302	hard or hardern\$4 or cure\$1 or curing	USPAT;	2004/09/01 13:02
			US-PGPUB;	
			EPO; JPO;	!
			DERWENT;	
			IBM TDB	
-	107409	((photoresist or resist or photosensitive	USPĀT;	2004/09/01 13:03
		or photo adj2 sensitive or polymeric) or	US-PGPUB;	
		polymer or polyimide) with (hard or	EPO; JPO;	
		hardern\$4 or cure\$1 or curing)	DERWENT;	
			IBM TDB	
-	114427	electroplat\$4 or electro adj2 plat\$4 or	USPĀT;	2004/09/01 13:04
		electrodeposit\$4 or electrol\$8 near3	US-PGPUB;	
		deposit\$4 or electrochemical\$2 near3	EPO; JPO;	
		deposit\$ or (electro adj1 chemical\$2)	DERWENT;	
		near3 deposit\$4	IBM_TDB	
-	5058080	groove or trench or hole or aperture or	USPĀT;	2004/09/01 13:04
1		opening	US-PGPUB;	
			EPO; JPO;	
1	1		DERWENT;	
			IBM_TDB	
-	251638	seed\$4	USPAT;	2004/09/01 13:05
	[US-PGPUB;	
	!		EPO; JPO;	
			DERWENT;	
			IBM_TDB	0004/00/00
-	2413		USPAT;	2004/09/01 13:07
		electrodeposit\$4 or electrol\$8 near3	US-PGPUB;	
		deposit\$4 or electrochemical\$2 near3	EPO; JPO;	
		deposit\$ or (electro adj1 chemical\$2)	DERWENT;	
		near3 deposit\$4) same (groove or trench	IBM_TDB	
1		or hole or aperture or opening) same		
		seed\$4		0004/00/01 14:10
-	12579	(metal\$4 or conduct\$4 or wire or wiring or	USPAT;	2004/09/01 14:12
		stud) with (pattern\$3) with (remov\$3) with	US-PGPUB;	
		((photoresist or resist or photosensitive	EPO; JPO;	
		or photo adj2 sensitive or polymeric) or	DERWENT;	
	1	polymer or polyimide)	IBM_TDB	2004/09/01 13:13
-	164	((electroplat\$4 or electro adj2 plat\$4 or	USPAT;	2004/09/01 13:13
	1	electrodeposit\$4 or electrol\$8 near3	US-PGPUB;	
		deposit\$4 or electrochemical\$2 near3	EPO; JPO; DERWENT;	
	1	deposit\$ or (electro adj1 chemical\$2) near3 deposit\$4) same (groove or trench	IBM TDB	
	1		1 TEL 1 DE	
	1	or hole or aperture or opening) same		
	1	seed\$4) and ((metal\$4 or conduct\$4 or wire or wiring or stud) with (pattern\$3)		
	1	with (remov\$3) with ((photoresist or		
		resist or photosensitive or photo adj2		
		sensitive or polymeric) or polymer or		
		sensitive or polymeric) or polymer or polymide))		
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